



DESCRIPTION

Lingsen' IDIP is a lead frame based, pre-housing package . It is available in pin count 8 and 12.

APPLICATIONS

- Mouse module

FEATURES

- Pin count range 8 and 12.

SPECIFICATIONS

Leadframe: 8/12L Material—NiPdAu or NiAuAg

Die Attach: CRM-1076WA

Gold Wire: 99.99%Au.

Pre-mold: MG350

Packing: Antistatic Tube.

PACKAGE AVAILABILITY

Package Size (mm)	Lead Pitch (mm)	Lead Count
9.1*9.91	2	8
10.16*11.69	1.778	12

RELIABILITY

Preconditioning Level4

Temperature Cycling -25°C/125°C, 1000 cycles.

Temp./Humid. Test 85°C/85% R.H., 1000hrs

High Temp. Storage 125°C,1000hrs

THERMAL PERFORMANCE

Package	Body size (mm)	Pad size (mm)	Die size (mm)	Thermal Performance ψ_{ja} (°C/W)
IDIP8L	9.1*9.91		1.4x1.7	
IDIP12L	10.16*11.69		1.5x1.8	

ELECTRICAL PERFORMANCE

Package	Body size (mm)	Pad size (mm)	Frequency (MHz)	Self inductance (nH)	Self capacitance (pF)	Resistance (mohm)
IDIP8L	9.1*9.91					
IDIP12L	10.16*11.69					

CROSS-SECTION